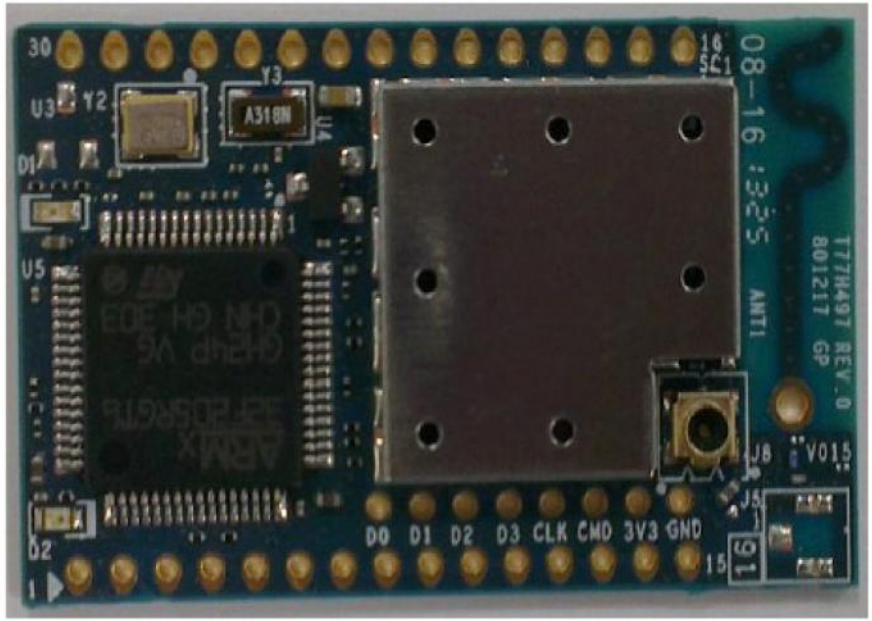
MXCHIP®
CONNECTING THE UNCONNECTED

EMW3162&EMW3280

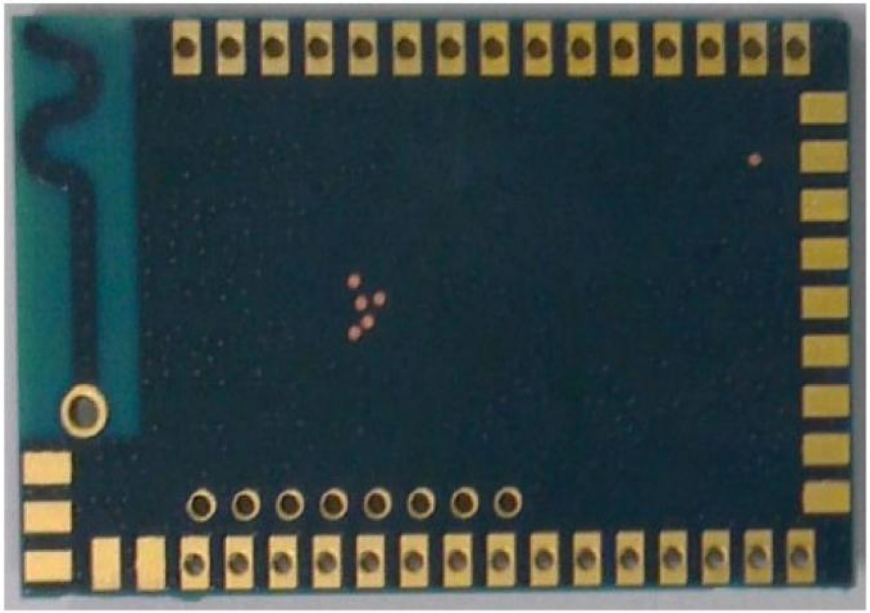
Assembly suggestions

MXCHIP®
CONNECTING THE UNCONNECTED

1 Sample picture is as below



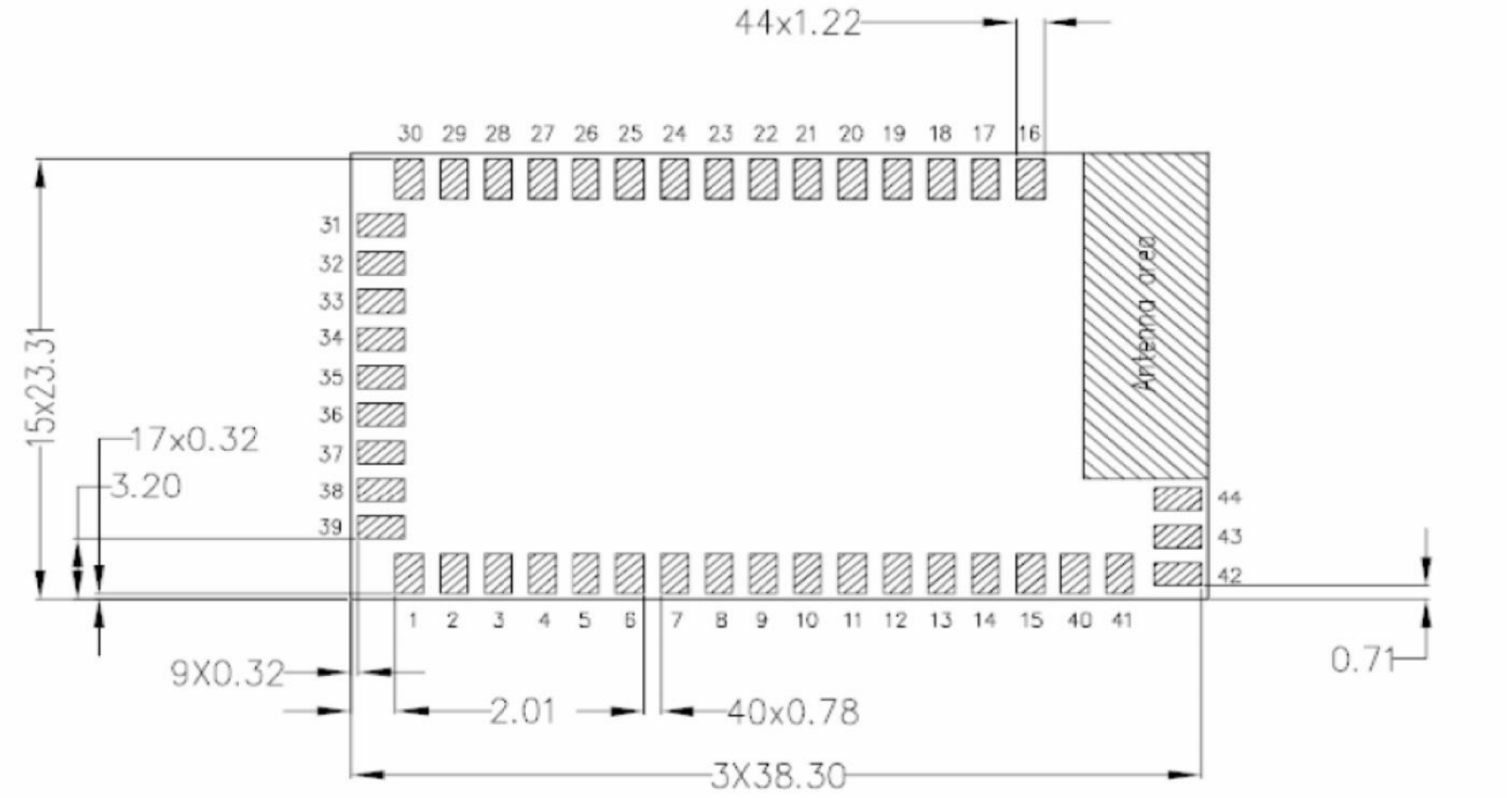
TOP



BOTTOM

1 QFN pad design

Below is for customer's motherboard QFN pad design, The pad design should be solder mask define.



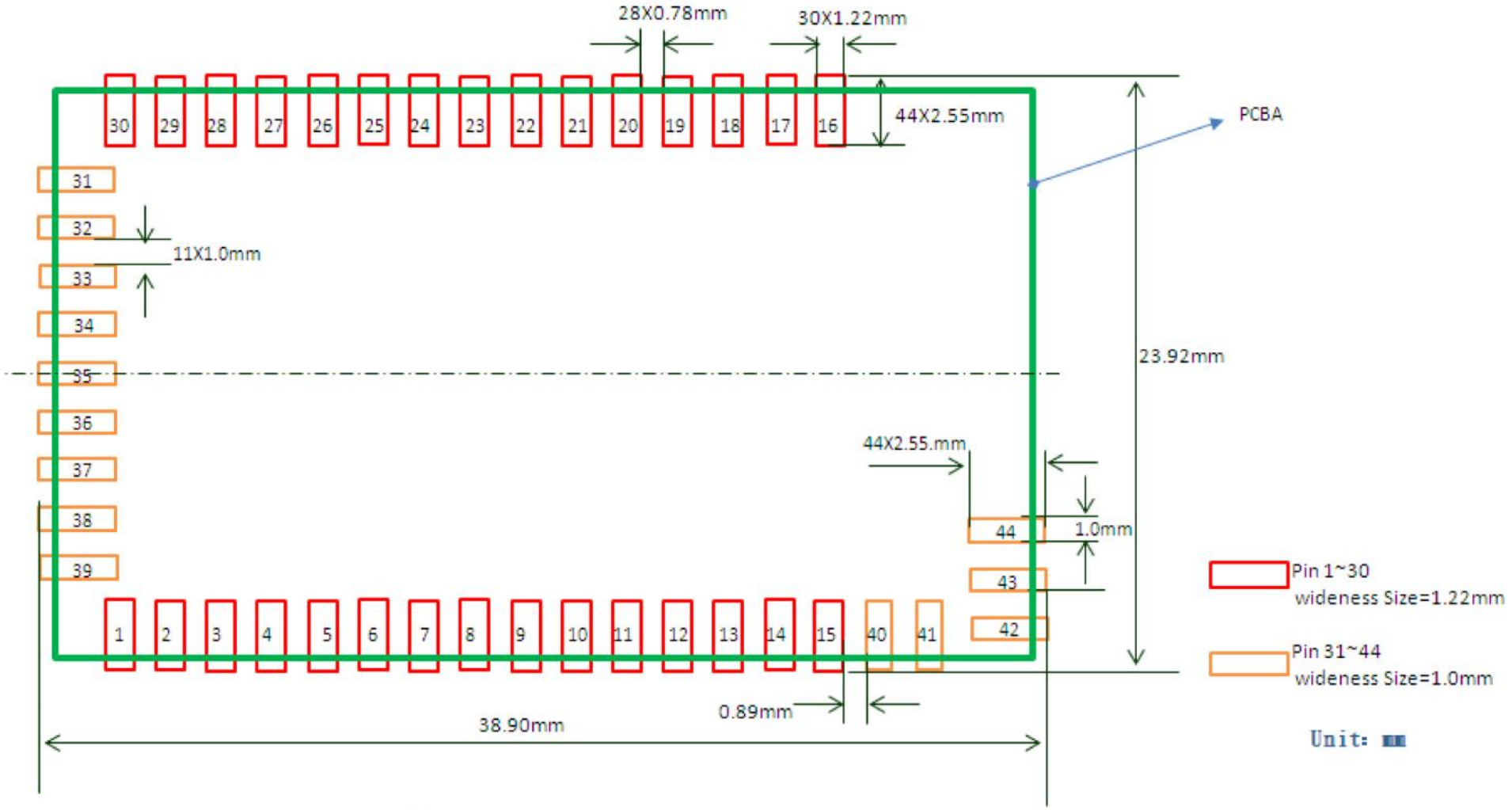
TOP View

2 Recommended Stencil pattern

MXCHIP®
CONNECTING THE UNCONNECTED

0.12mm stencil thickness, laser cut apertures, Trapezoidal walls and rounded corners offer better Paste release, stencil as picture 1.

Remark ：All pin length =2.55mm；Pin 1~30：wideness Size=1.22mm； Pin 31~44：wideness Size=1.0mm



picture 1.

3 Recommended reflow profile

MXCHIP®
CONNECTING THE UNCONNECTED

Solder paste recommendations: SAC305, Lead -Free solder paste.

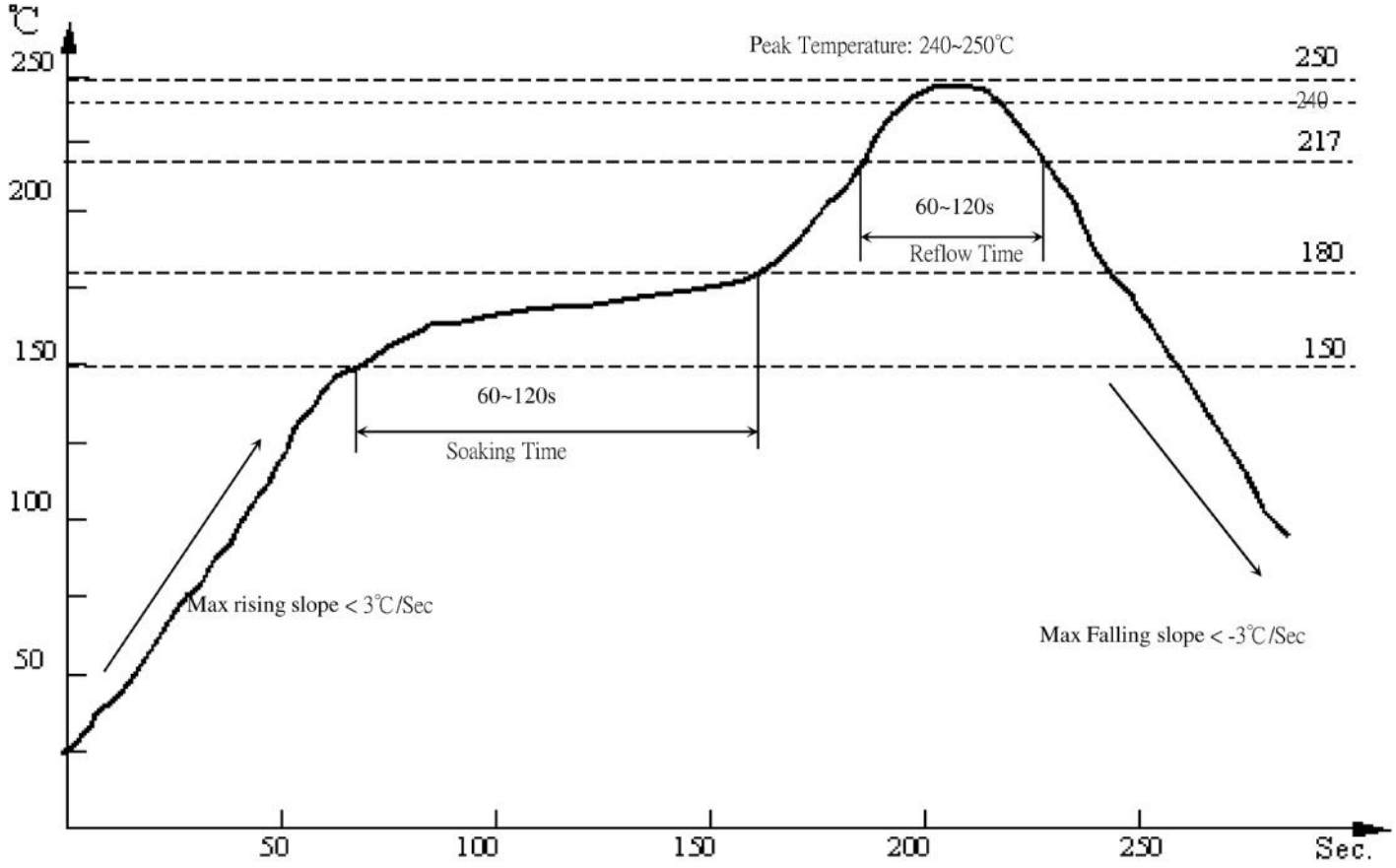
1.Max Rising Slope : 3℃/sec

2.Max Falling Slope: -3 ℃/sec

3.Soaking Time(150℃~180℃): 60sec~120sec

4.Over 217℃ Time:60sec~120sec；

5.Peak Temp.240℃~250℃



4 MSL/storage Condition

CAUTION

This bag contains
MOISTURE-SENSITIVE DEVICES

LEVEL **3**

If Blank, see adjacent bar code label

1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH)
2. Peak package body temperature: 250 °C
   If Blank, see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
   a) Mounted within: 168 hrs. of factory conditions
      If Blank, see adjacent bar code label
      ≤ 30°C/60%RH, OR
   b) Stored at <10% RH
4. Devices require bake, before mounting, if:
   a) Humidity Indicator Card is > 10% when read at 23 ± 5°C
   b) 3a or 3b not met.
5. If baking is required, devices may be baked for 48 hrs. at 125 ± 5°C

   Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: _____
If Blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020